



**Carleton**  
UNIVERSITY



# Upgrade of the ATLAS Muon Spectrometer Thin Gap Chambers and their electronics for the HL-LHC phase

Chav Chhiv Chau, on behalf of of the ATLAS Muon Collaboration

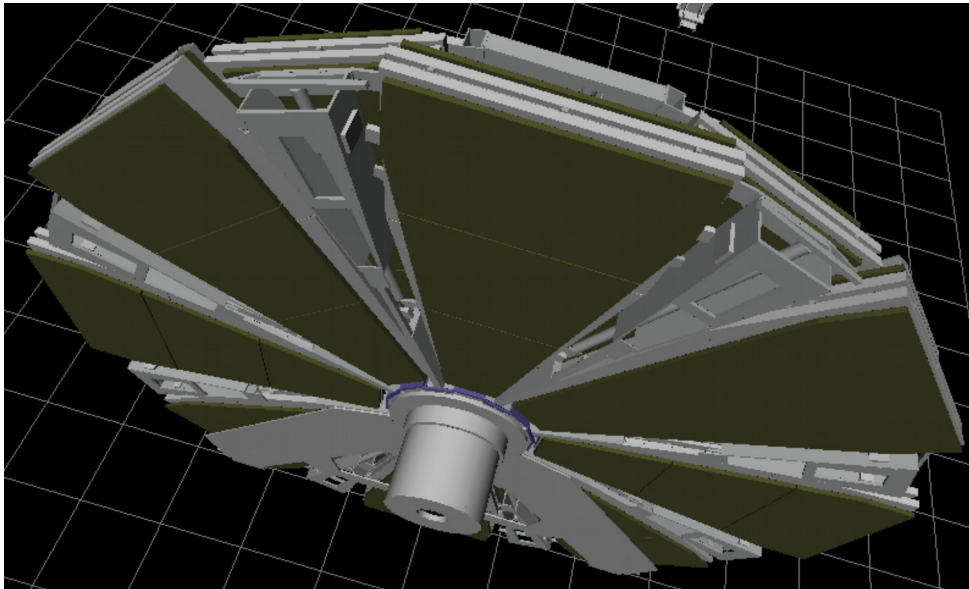
VCI 2019

21 February 2019

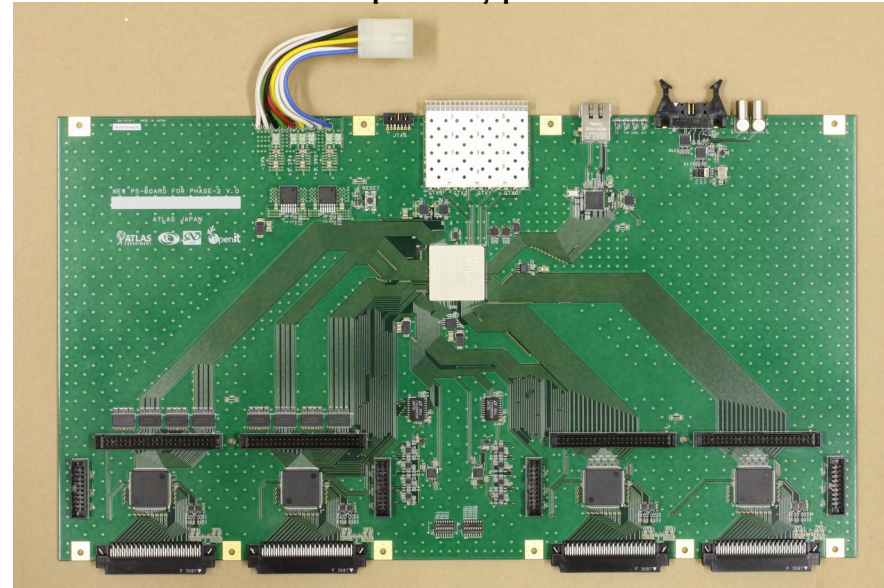
# Outline

- ATLAS upgrade projects
- sTGC-NSW upgrade project
- Replacement of the EIL4 TGC chambers
- Upgrade of the TGC electronics
- Summary

A NSW in the ATLAS simulation

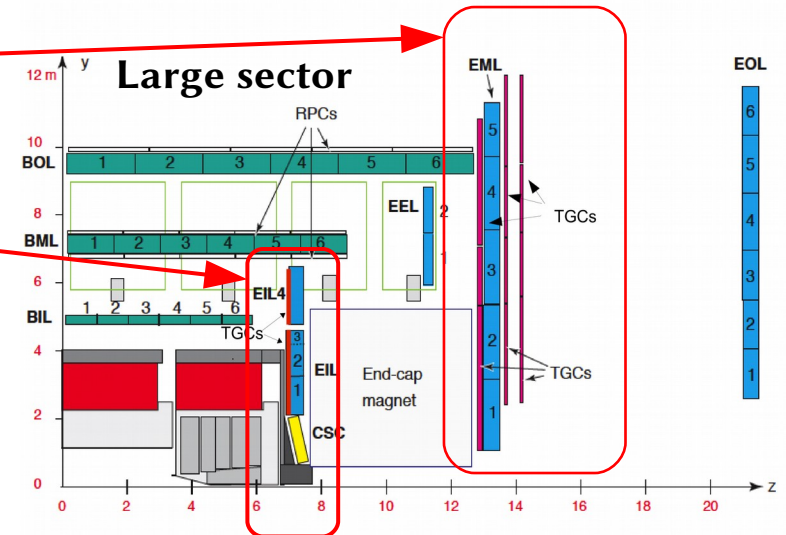
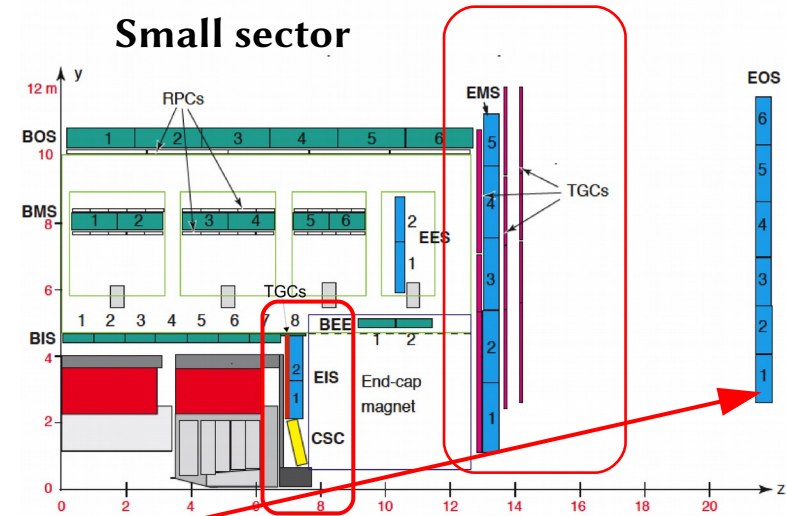
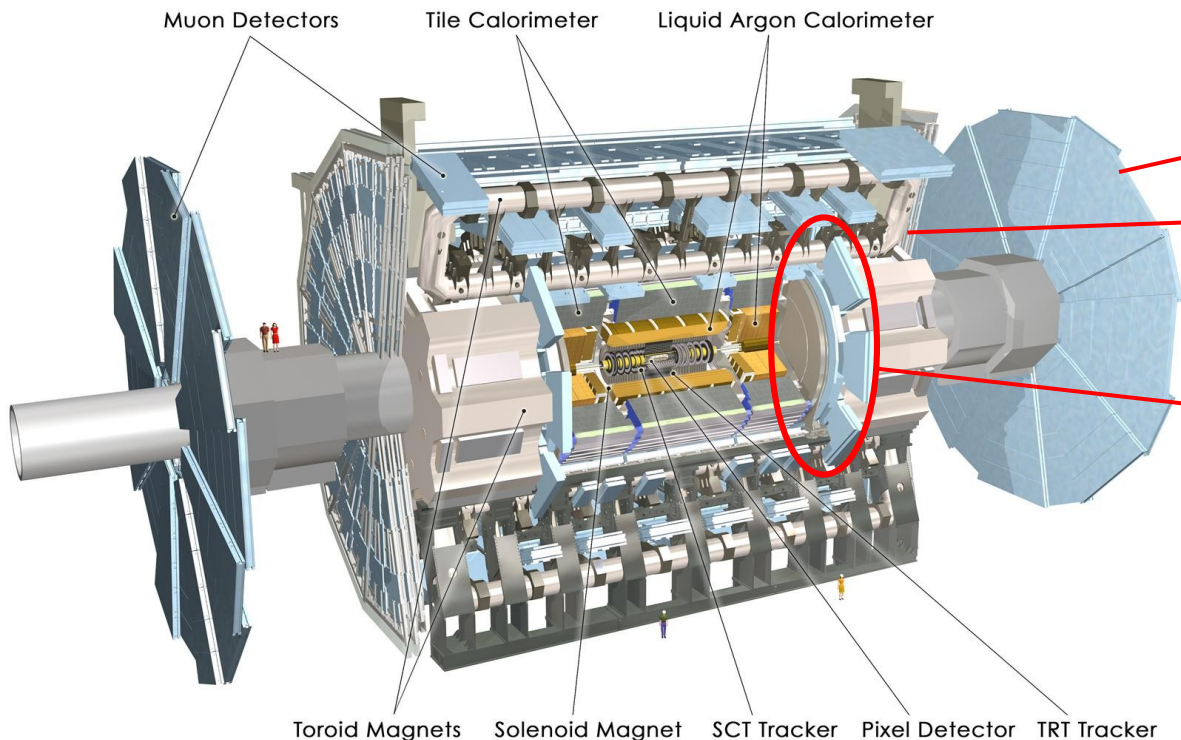


PS prototype board for the TGC



# ATLAS detector

- Great operation in Run1 and Run2
  - For example, more than 99% of TGC chambers were operational



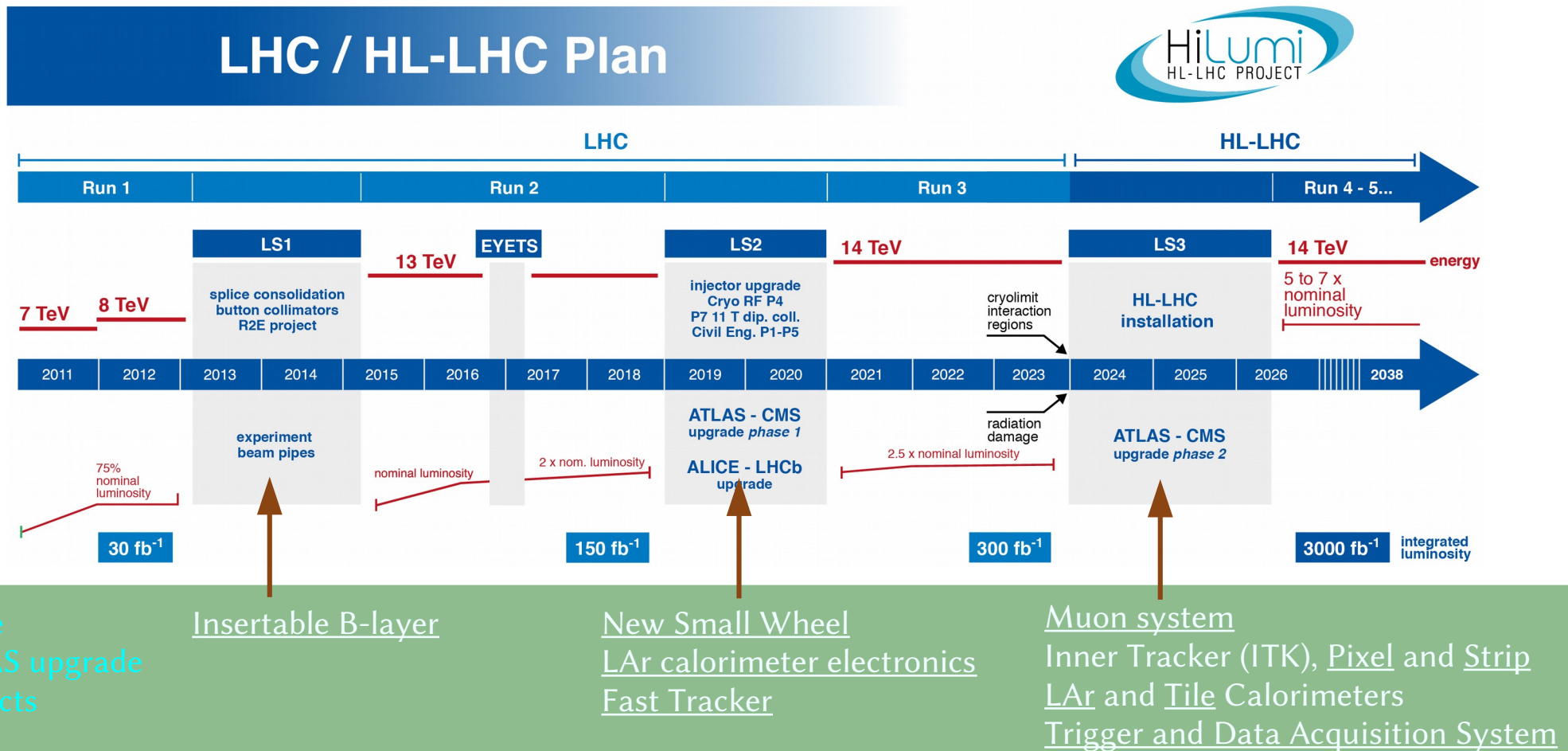
Small Wheel and EIL4

Two R-Z views of the present muon spectrometer



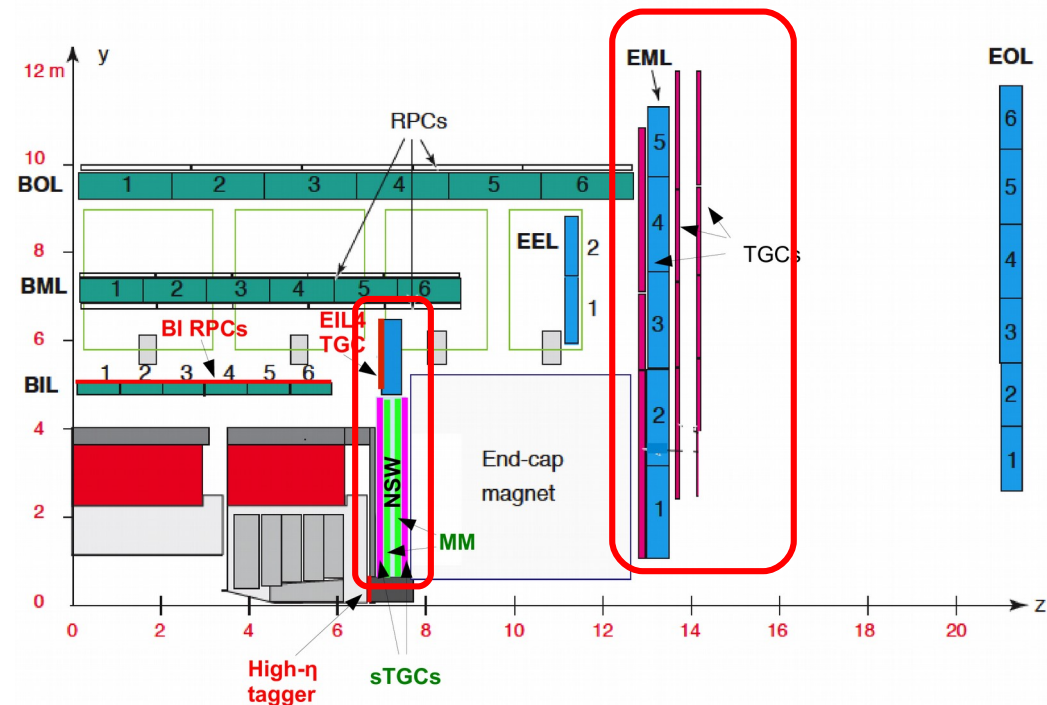
# LHC Plan

- Instantaneous luminosity to reach  $7.5 \times 10^{34} \text{ cm}^{-2}\text{s}^{-1}$  at HL-LHC
  - Total integrated luminosity:  $3000 \text{ fb}^{-1}$  after 10 years (in 2036)
  - Average pile-up of 200 interactions



# Upgrade of ATLAS Thin Gap chambers

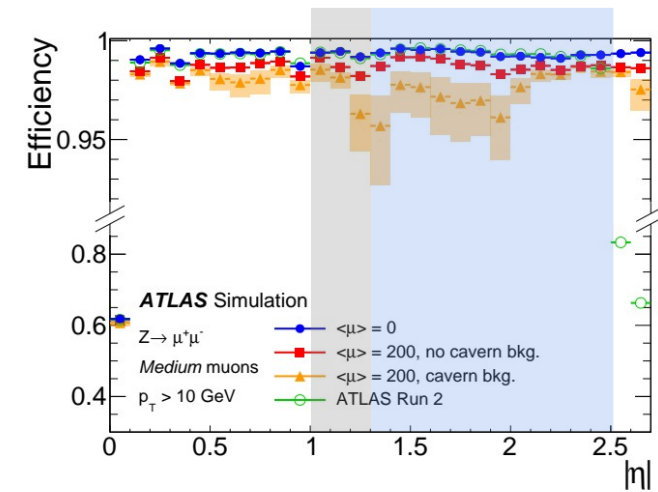
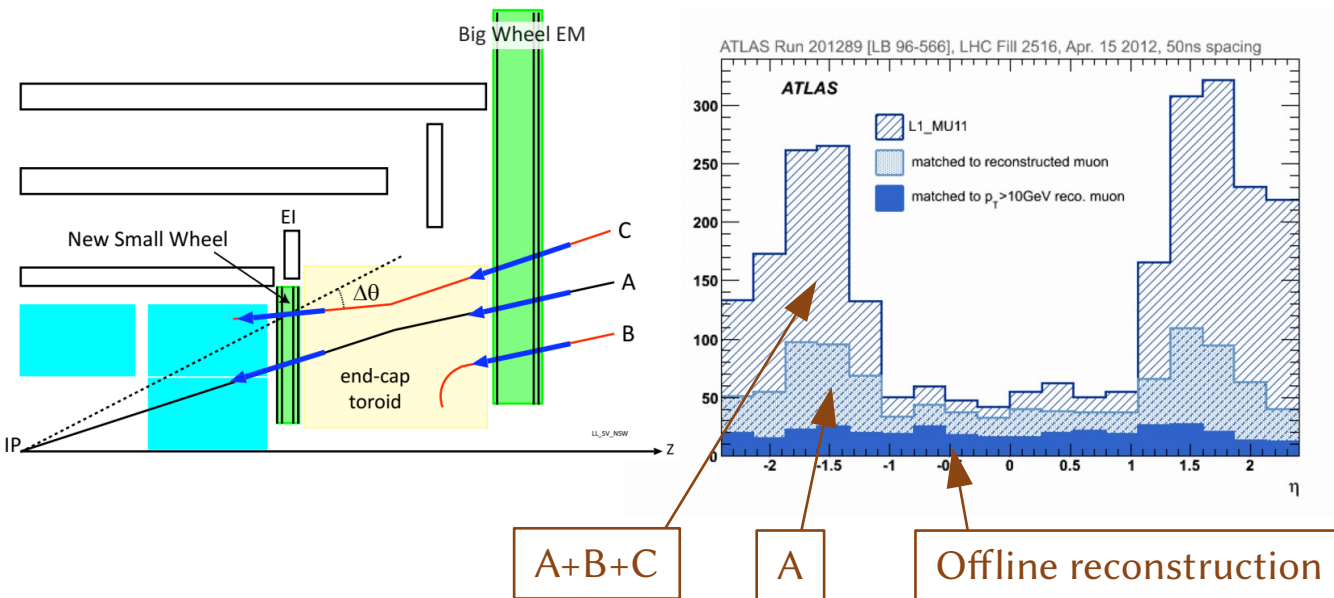
- Phase-I, NSW TDR: [ATLAS-TDR-020](#)
  - Replacing the innermost muon end-cap station with the New Small Wheels (NSWs), which have small-strip TGC and MM
- Phase-II, muon TDR: [ATLAS-TDR-026](#)
  - Replacing the EIL4 TGC, innermost endcap station
  - Replacing the electronics of the TGCs at the 2<sup>nd</sup> muon station



Layout of the Phase-II ATLAS muon spectrometer

# Current TGC at high event pileup

- Currently, endcap trigger decision is based on the big wheel TGCs



Trigger efficiency **without** the EIL4 replacement (1.0-1.3) and NSW (1.3-2.5)

- Trigger efficiency drops significantly in the endcap region due to cavern background

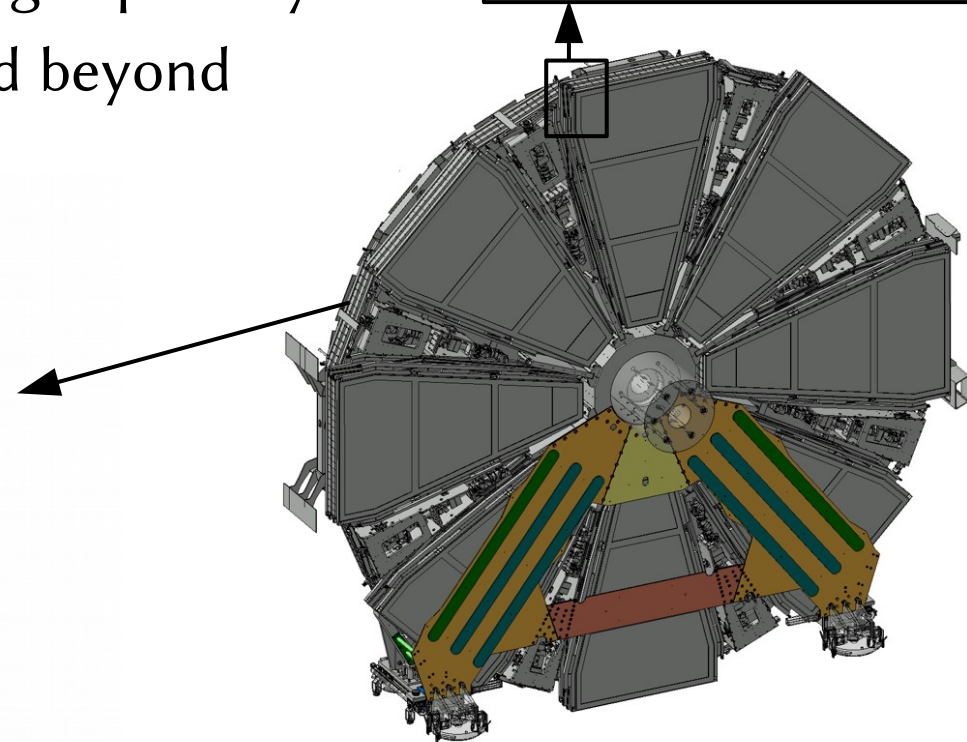
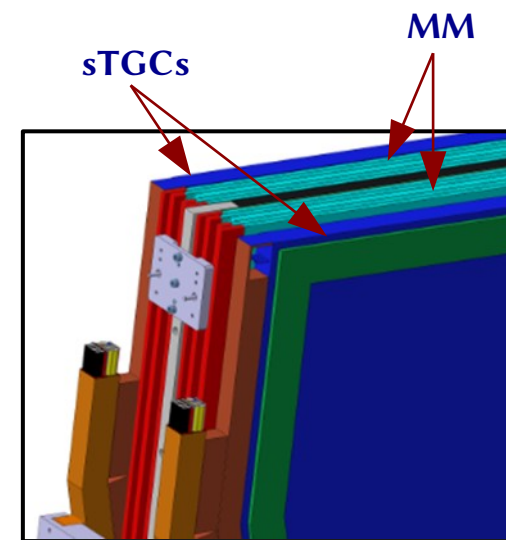
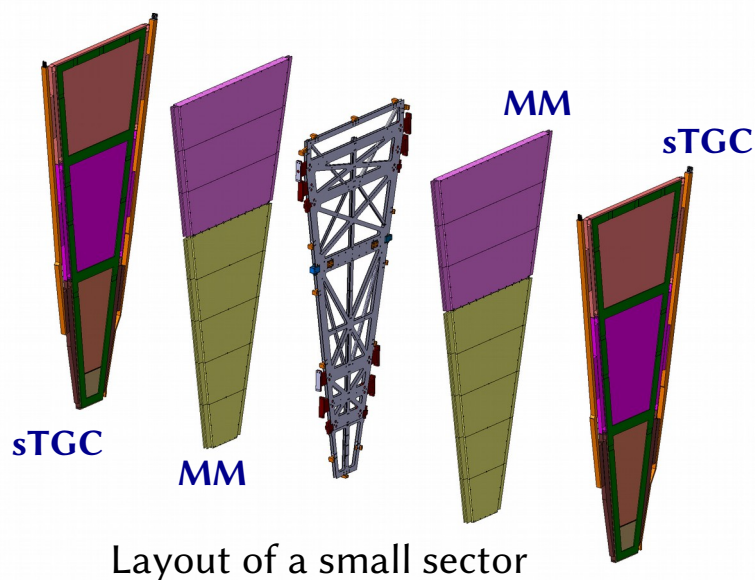
[ATLAS-TDR-020](#)

[ATLAS-TDR-026](#)

# Phase-I ATLAS small-strip Thin Gap Chambers

# ATLAS New Small Wheel

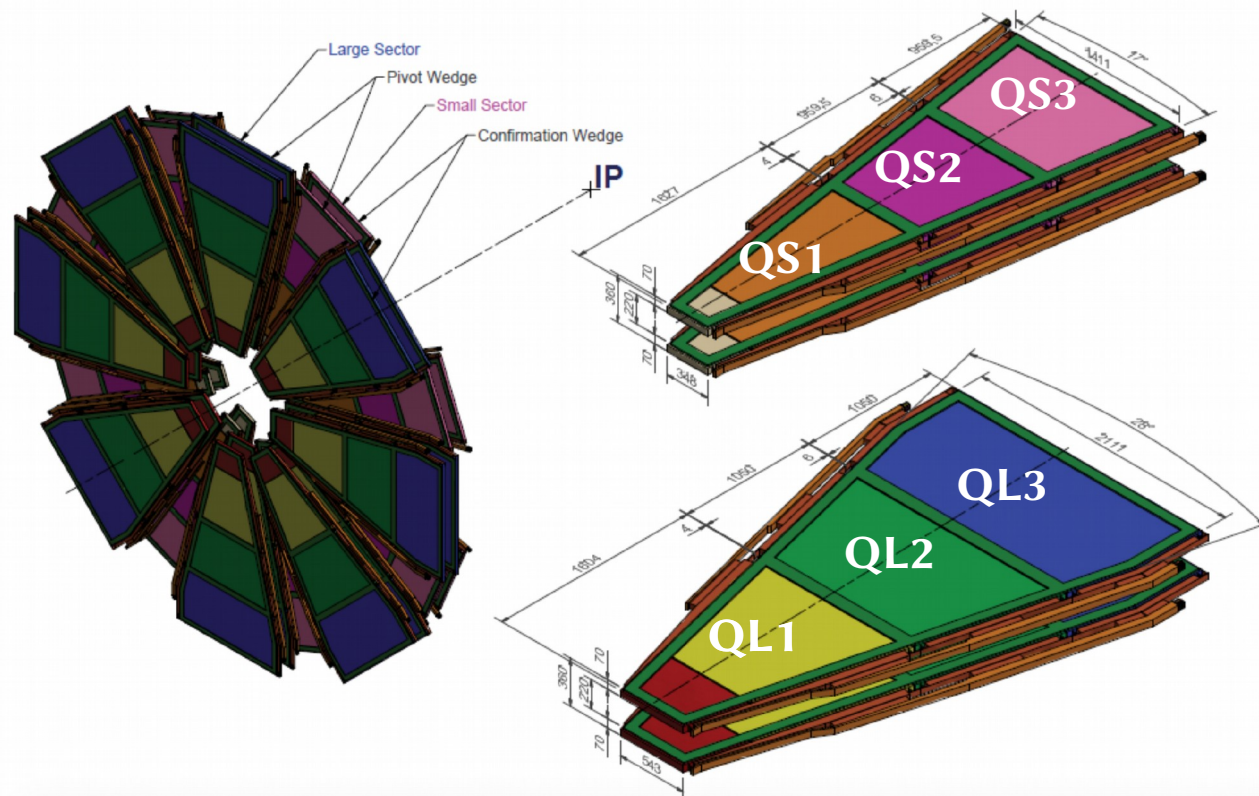
- NSW has 2 gaseous chamber technologies
  - small-strip **T**hin **G**ap Chamber (sTGC)
  - **M**icromegas (MM)
- NSW is designed to provide
  - High-precision trigger and tracking capability
  - To operate efficiently at Run-3 and beyond





# sTGC detector

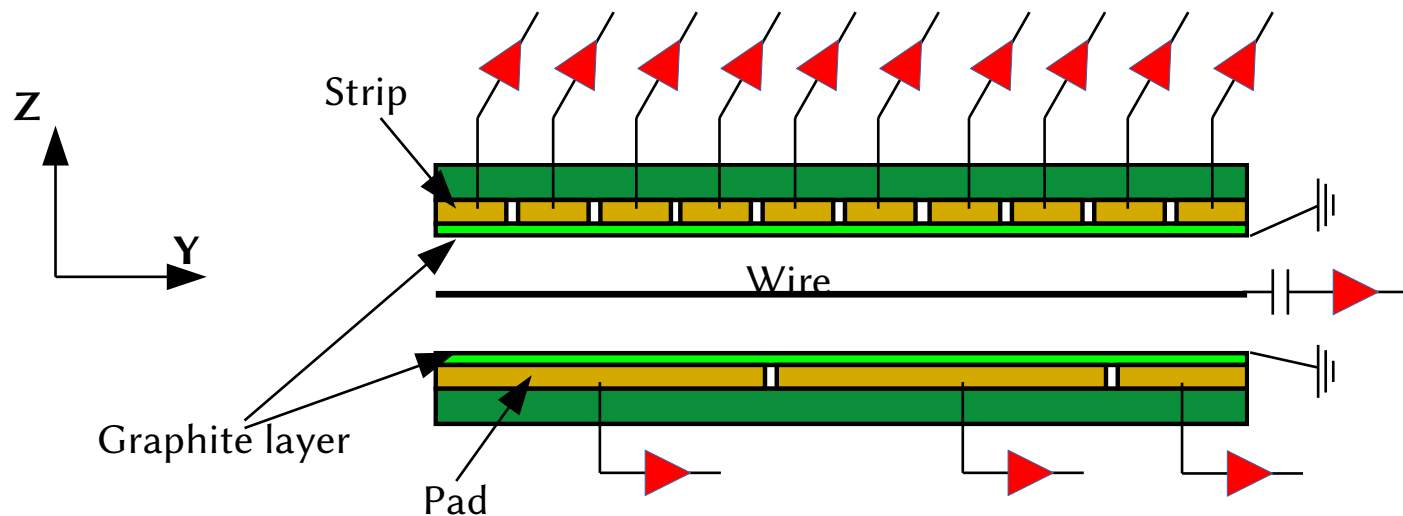
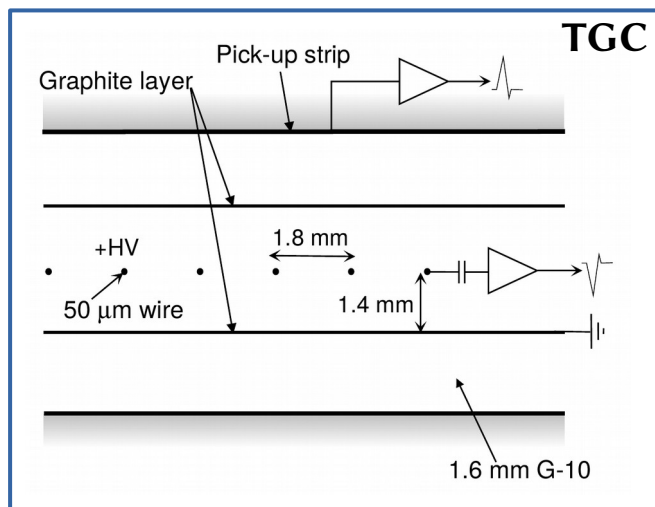
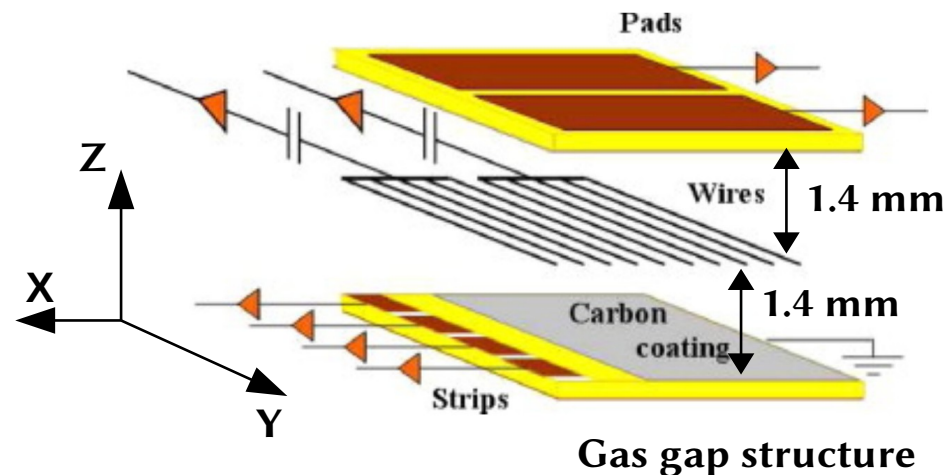
- Used for both muon triggering (primary trigger device for NSW) and precision tracking in regions  $1.3 < |\eta| < 2.5$
- Designed to provide angular resolution better than 1 mrad
- Two wedges of 4 layers each, for a total of 8 gas chambers



Construction sites	
Canada	1/2 QS3 and QL2
Chile	QS1
China	QS2
Israel	1/2 QS3 and QL1
Russia	QL3

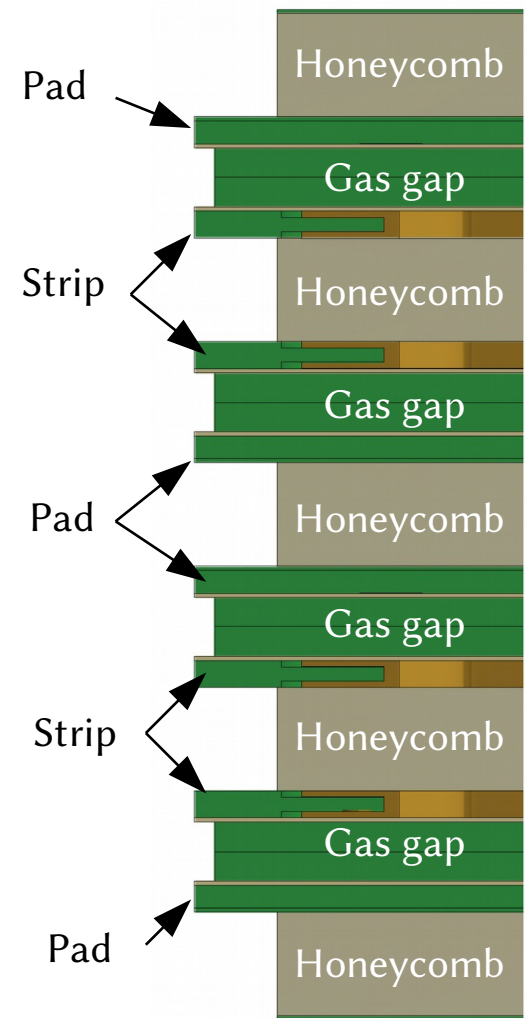
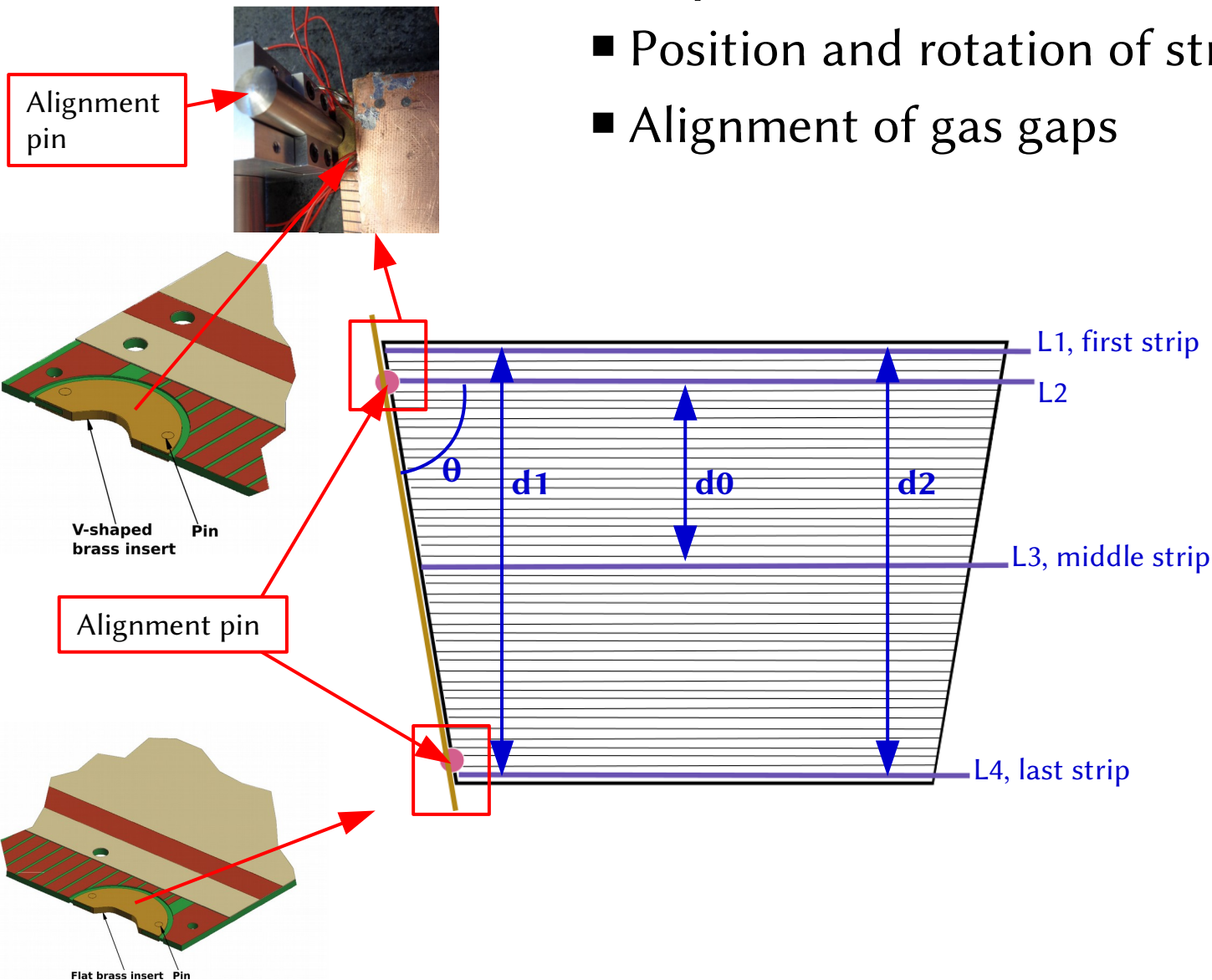
# sTGC internal structure

- Pads: mainly for triggering
- Wires: azimuth coordinate
  - 50  $\mu\text{m}$  gold-plated tungsten
  - 1.8-mm pitch
- Strips: eta coordinate
  - pitch of 3.2 mm,
  - providing spatial resolution better than 150  $\mu\text{m}$
- Gas mixture: 55%  $\text{CO}_2$  and 45% n-pentane



# STGC alignment

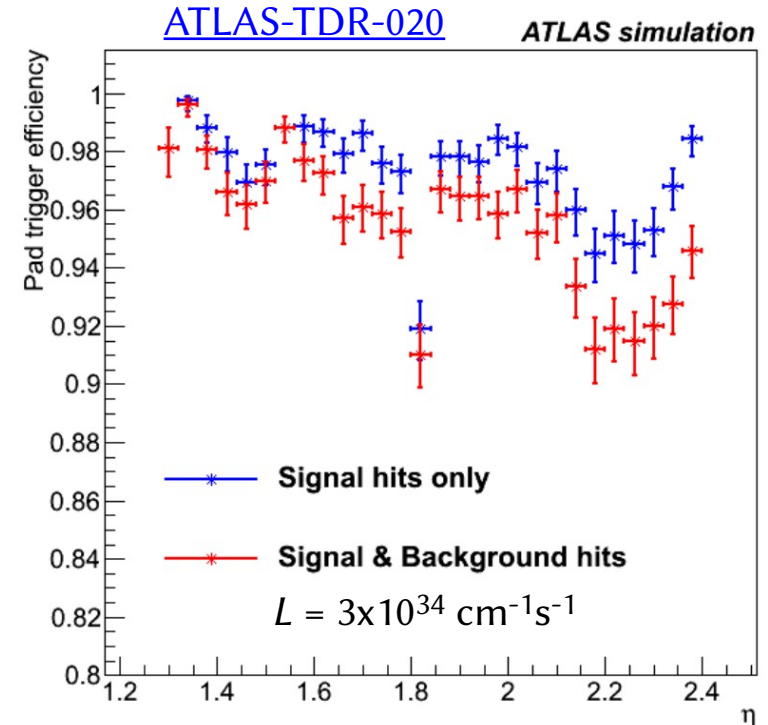
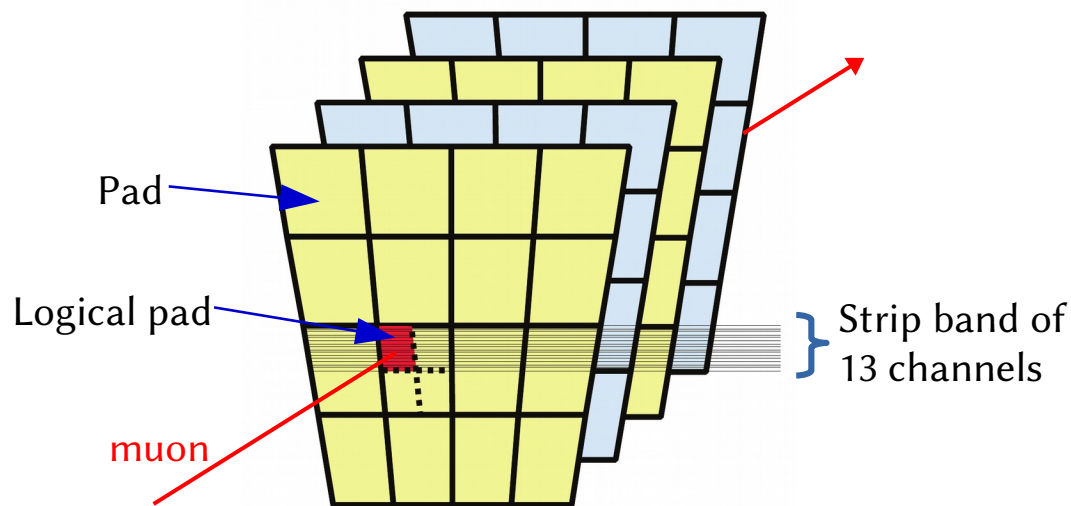
- V-shaped and flat brass inserts
  - Position and rotation of strips
  - Alignment of gas gaps



Layout of one quadruplet

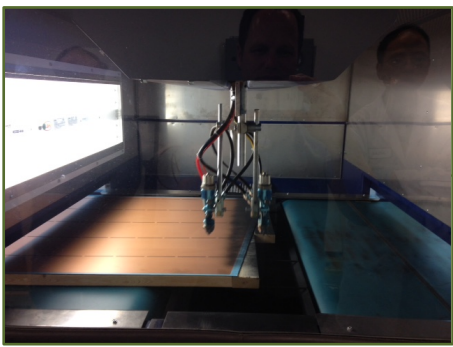
# sTGC Trigger

- Pad layers are staggered by half a pad to make “logical” pad towers
- Trigger algorithm consists of two steps:
  - Independent single wedge trigger: require hit in 3 out of 4 layers
  - Pad trigger: decision based on geometrical matching between the two wedge triggers



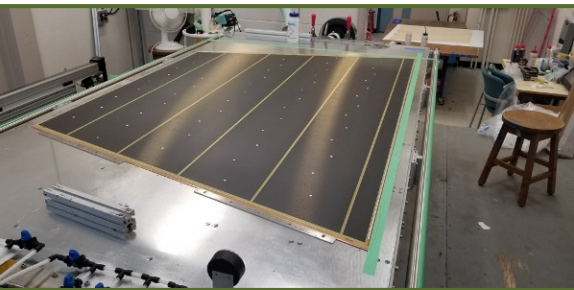


# sTGC construction



Graphite spraying

Half-gap production

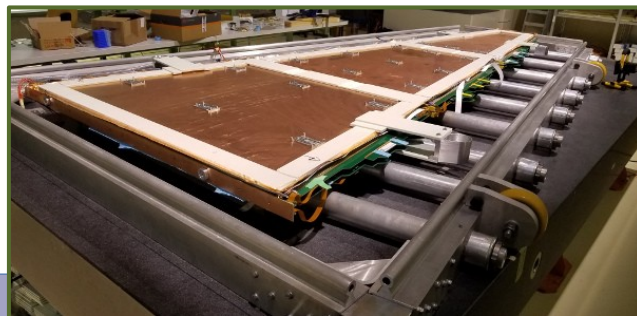


Wire winding of pad cathodes

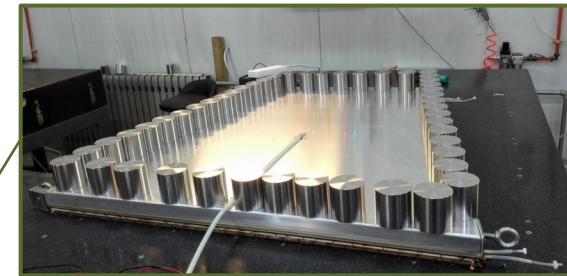
Gap closing



Gap testing



Doublet assembling

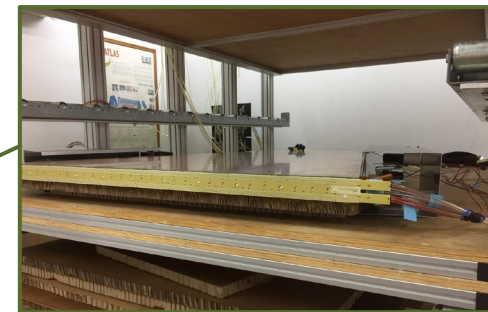


Doublet testing

Quadruplet assembling



Adapter board mounting

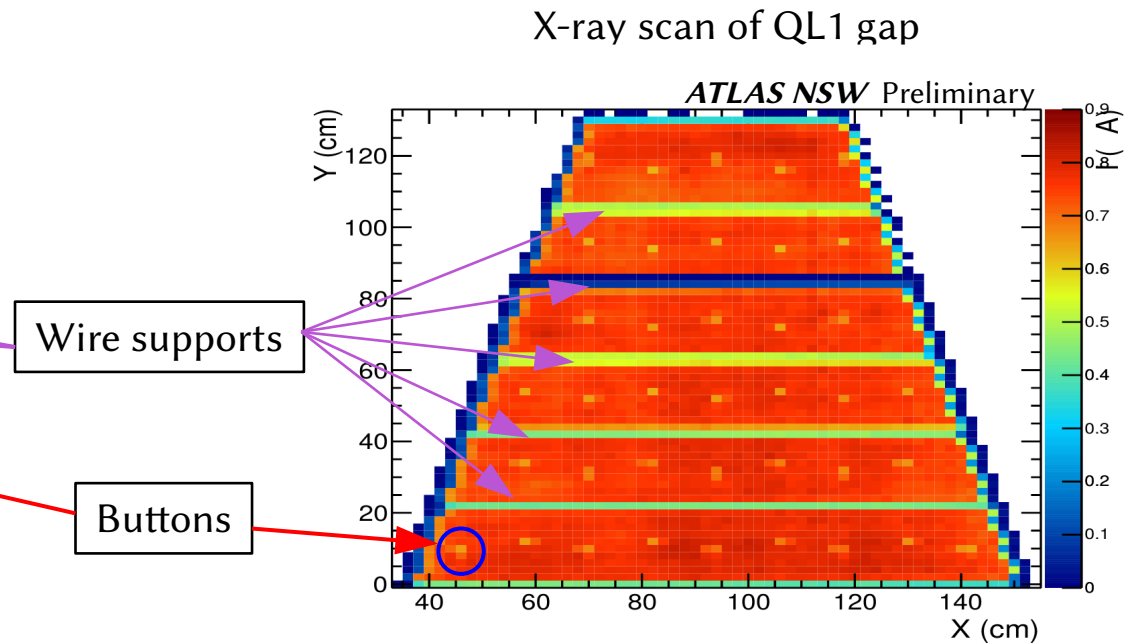
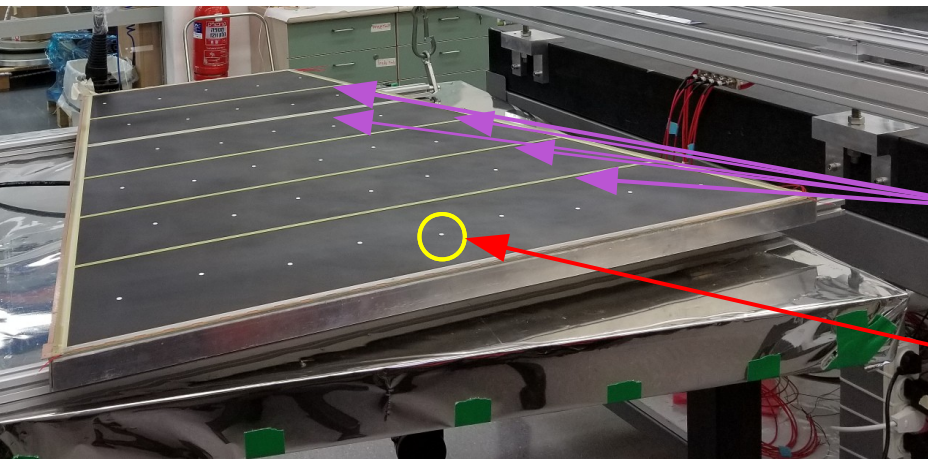


Cosmic-ray testing

Wedge assembly and integration (CERN)

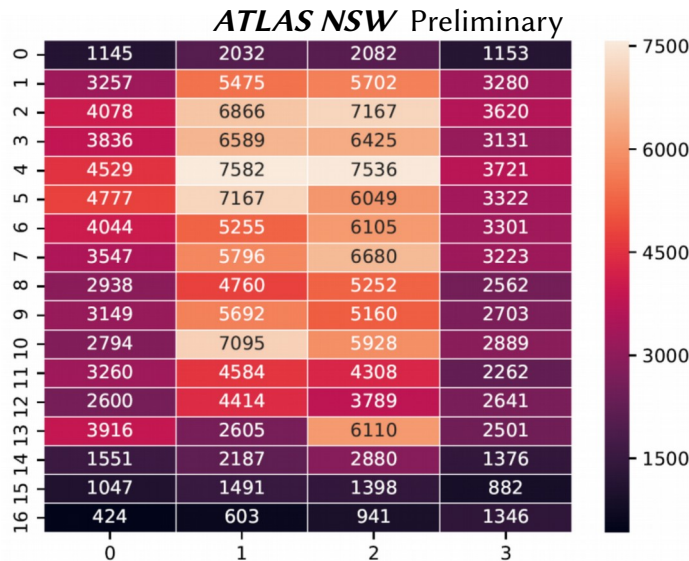
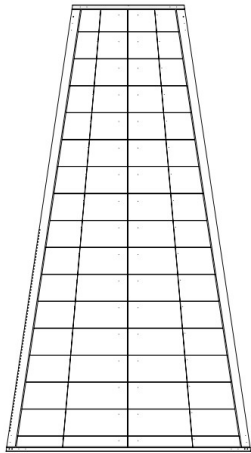
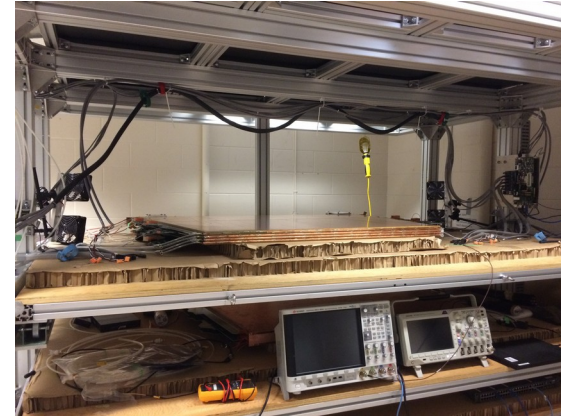
# X-ray scans

- Measure gain uniformity of gas gaps at 3200 V
- Probe internal structure of gaps
- Gaps with poor gain uniformity are rejected



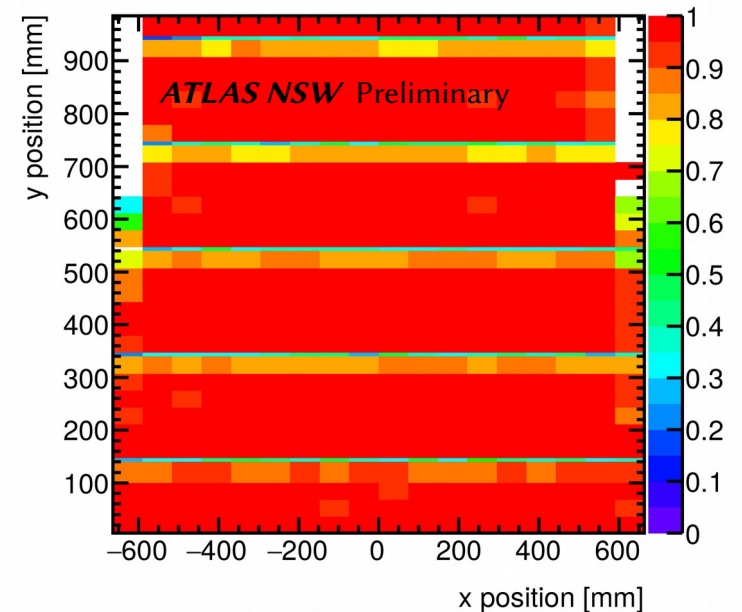
# Cosmic tests

- Hit maps
- 2D efficiency maps
- Noise measurement
- Spatial resolution and misalignment correction



Number of cosmic muons counted in a QS1 gap during a period of approximately 13 hours

- Low hit count on the edges due to the finite size of the scintillators

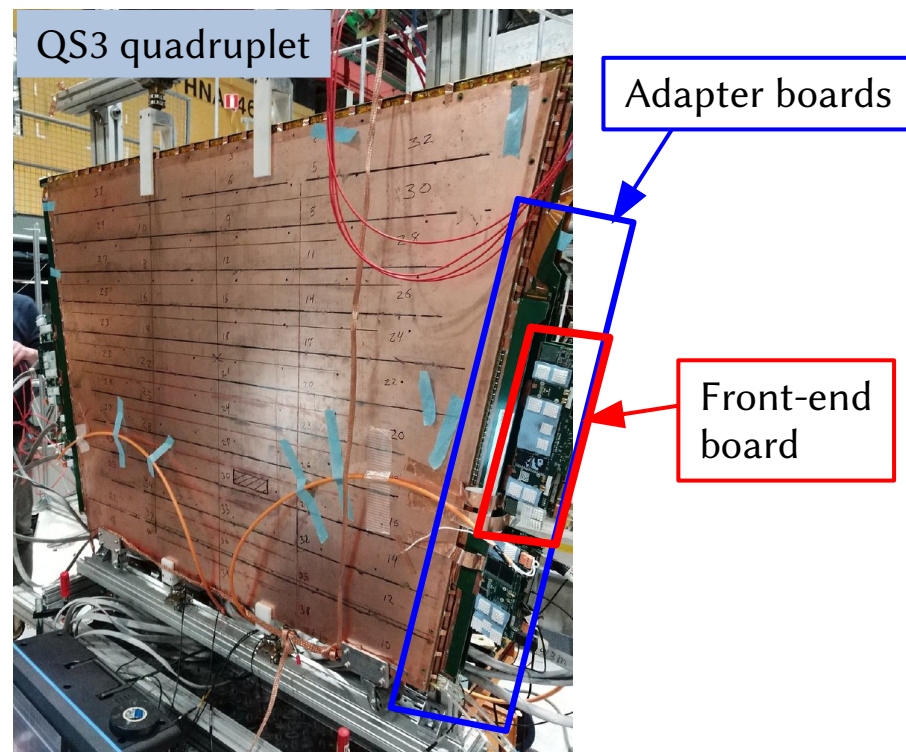
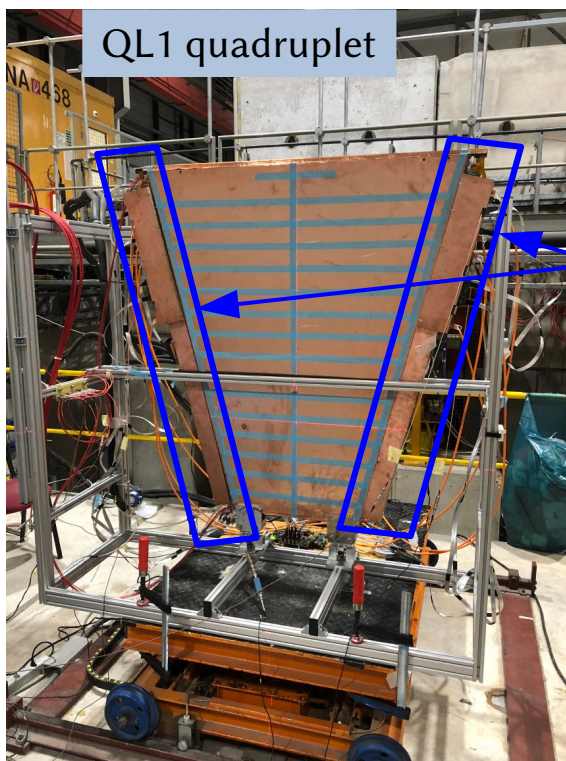


Preliminary 2D efficiency of strip channels of a QS3 gap at a operation voltage of 3100 V.



# STGC testbeam at CERN

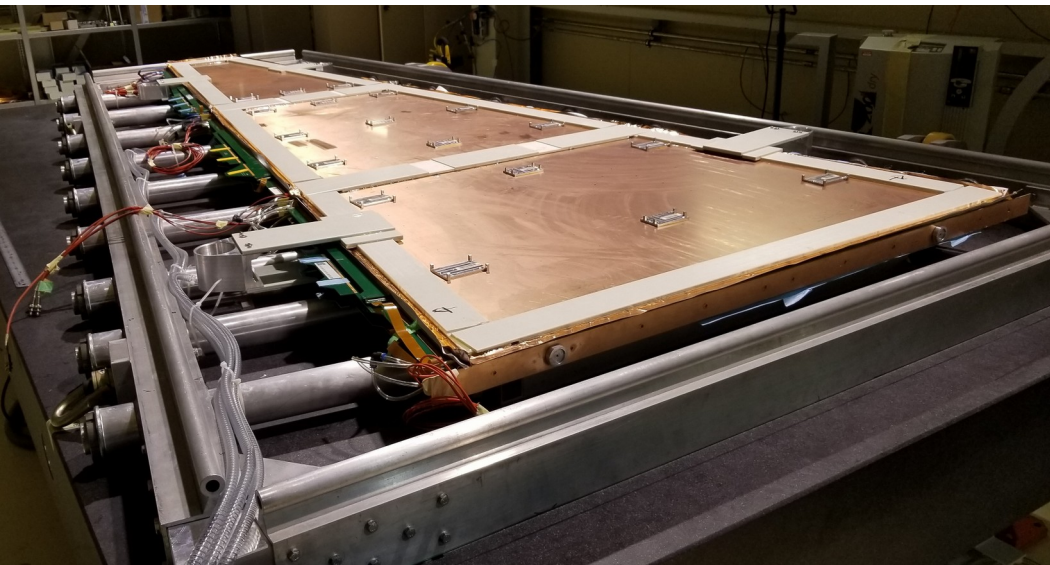
- Three quadruplets tested with beam at CERN in October 2018
  - Quadruplets instrumented with 4 pad and 4 strip front-end boards
  - Data taken at 2.8 kV, 2.9 kV, 3.0 kV and 3.1 kV
  - Studies of gap efficiency and strip resolution
    - Analysis of data is ongoing





# Integration at CERN

- Assemble sTGC quadruplets into wedges
- Install the electronics and services
- Integrate sTGC and MM into sectors
- Wheel assembly



Assembly of a small sTGC wedge

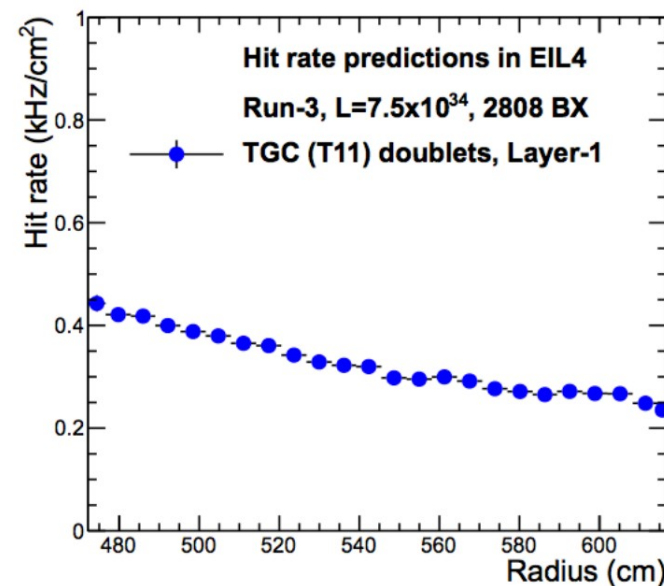
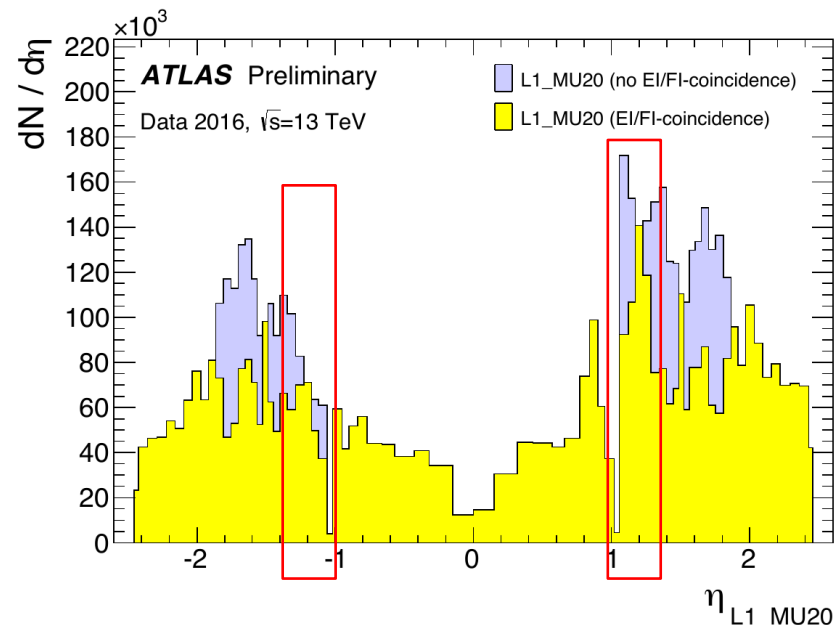


Both new JDs with spokes for small sectors

# Phase-II TGC Upgrade Projects

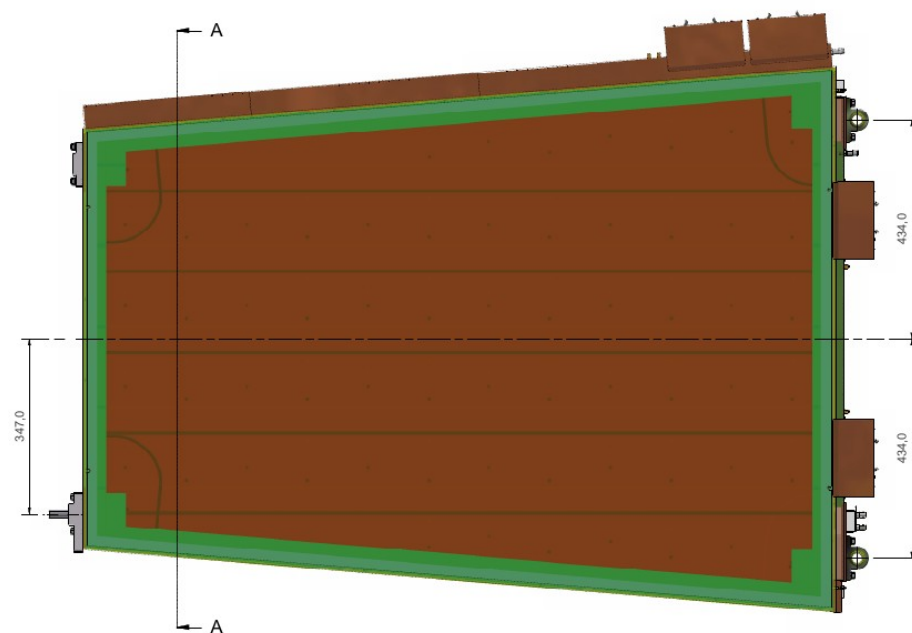
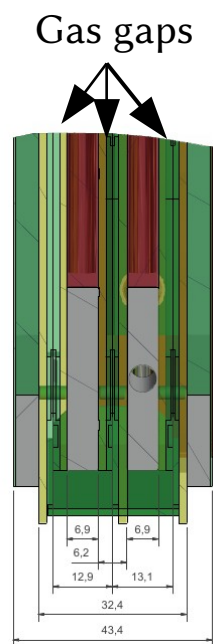
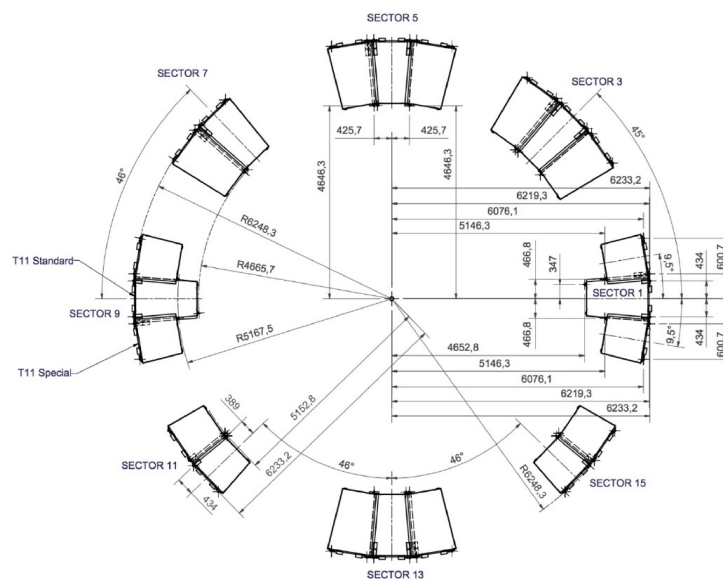
# ATLAS EIL4 TGC

- EIL4, made of two gas gaps, are not designed to be part of the trigger system in the endcap region
  - Region of interest of  $\sim 1 \text{ m}^2$
- EIL4 hit data can reduce significantly the fake trigger rate
  - Providing an extra OR logic to the trigger system
- High hit rate at the HL-LHC degrades the rejection power of the current EIL4 TGC



# Design of Phase-II EIL4 chambers

- Replace current EIL4 TGC (doublets) with triplet thin gap chambers
  - Finer granularity
  - More robust 2 out of 3 coincidence
- Expect the project to ramp up after the sTGC production is over





# TGC trigger for the HL-LHC

- Maintain trigger rates of single muons with low momentum at manageable level at the HL-LHC
- Upgrade to modern electronics
  - Increase trigger rate capacity up to 4 MHz (first-level trigger)
  - Allow robust trigger algorithm

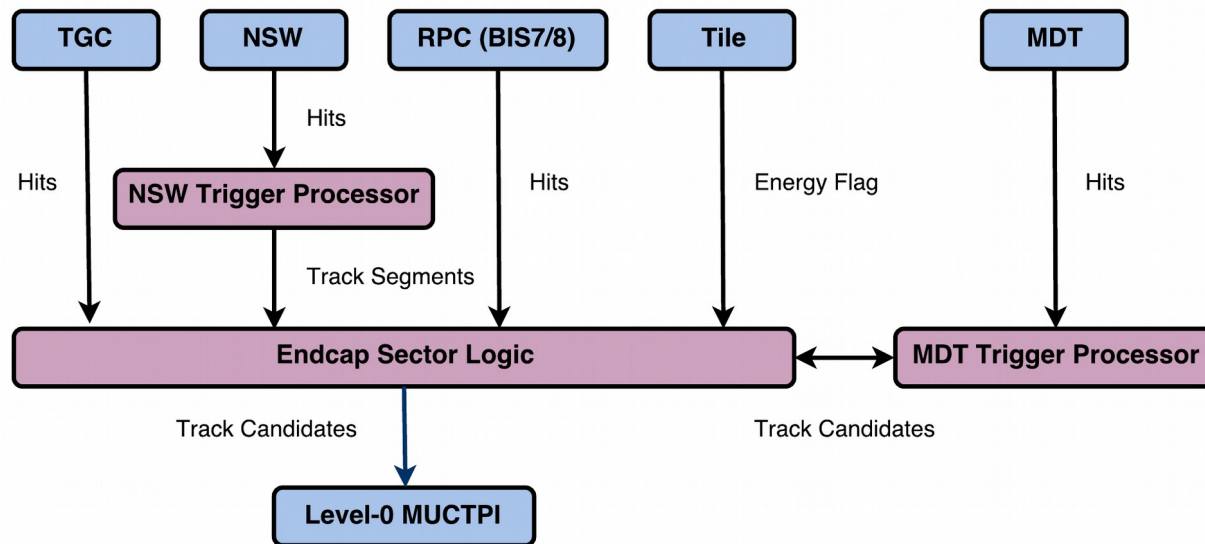
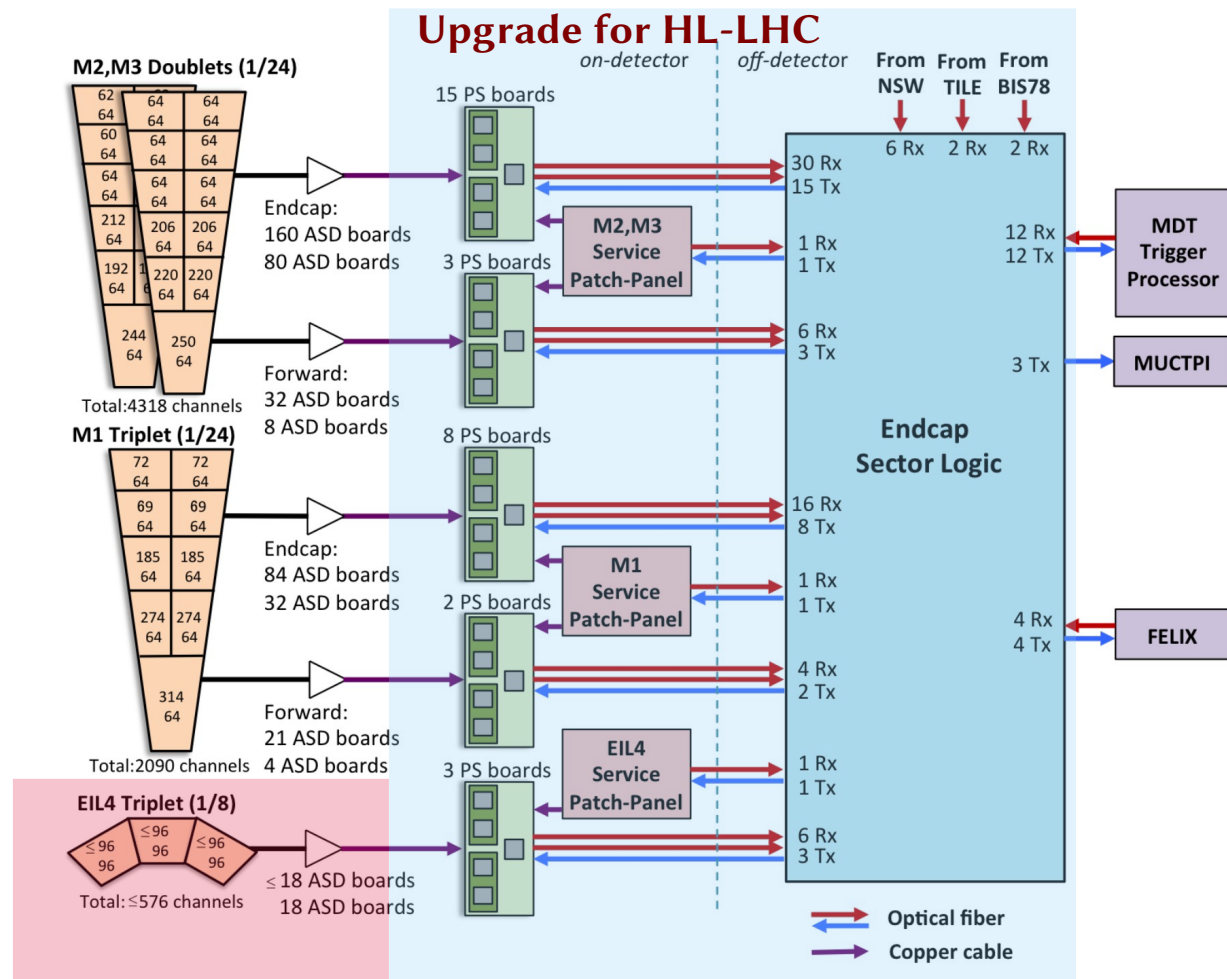


Diagram of proposed first-level trigger logic

# Upgrade of the TGC electronics

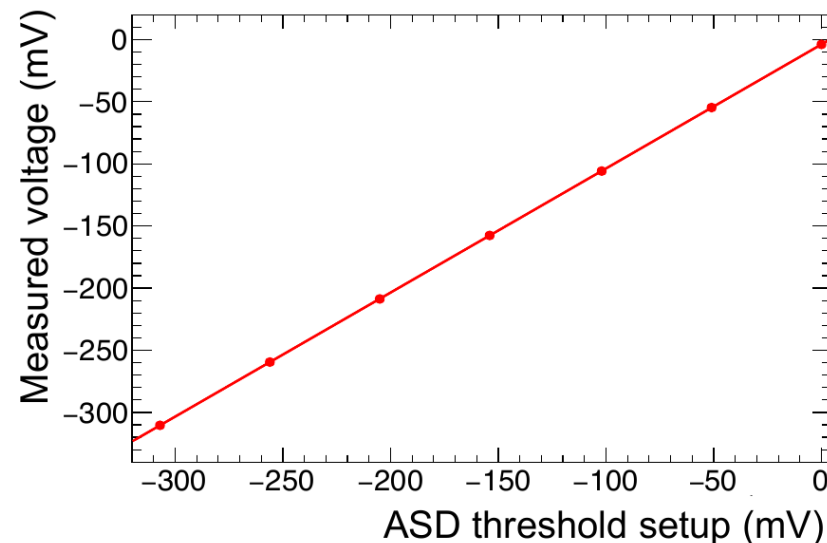
- All TGC electronics will be replaced, except the ADS boards
- Development is underway
- Prototypes of PS boards are produced with all requirements for HL-LHC
- Testbeam and irradiation tests done



ASD: Amplifier-shaper-discriminator  
PS: Patch Panel ASIC and Slave ASIC

# Testing of a PS prototype board

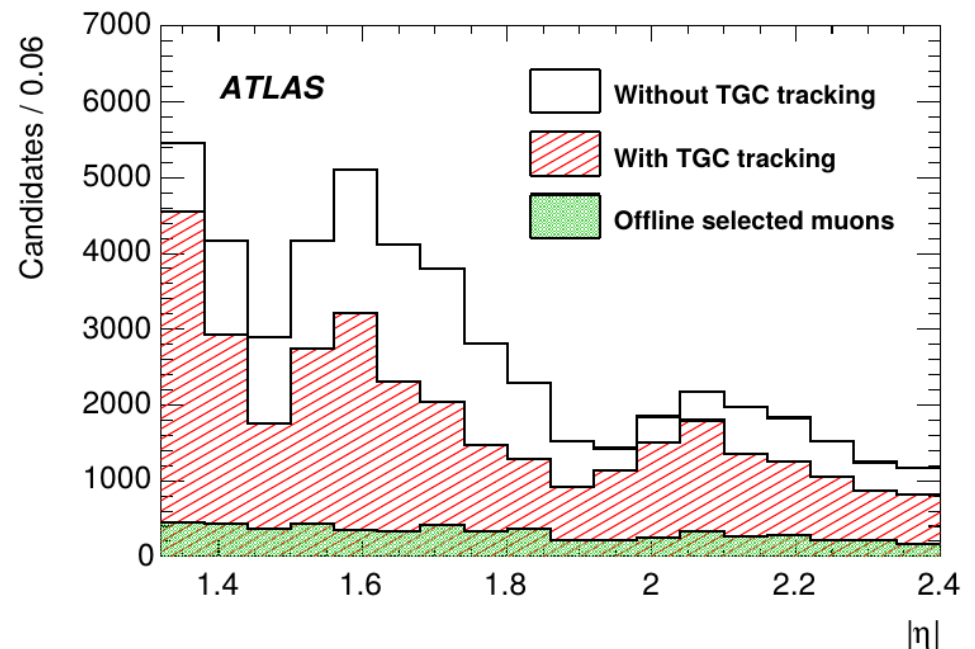
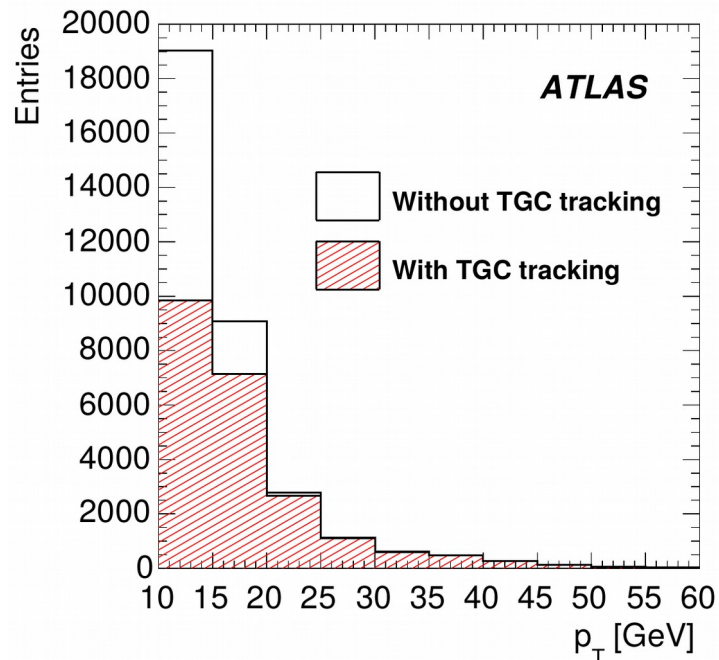
- Test of a prototype board at the H8 beam line at CERN done in Fall 2016
  - Demonstrate stable data transfer of 2 x 8 Gbps, and control and monitor of ASD boards through PP-ASIC
- Gamma irradiation test of PS board components (PP-ASIC, DAC and ADC chips) at Nagoya University
  - Demonstrate all components satisfy the requirements for the HL-LHC



	Ionizing dose	Requirement for HL-LHC
PP-ASIC	10 kGy	27 Gy
DAC, ADC	180 Gy	180 Gy

# Phase-II TGC trigger performance

- Upgrade sector logic to exploit all hits available
  - Replace current TGC logic ( 2/3 & 3/4 coincidence) with track segment with requirement on number of hits (hits in at least 5 of the 7 layers)
- Combine NSW track segment with TGC track segment
  - Reduce trigger rate by 30%, mainly by eliminating fake triggers, in the region  $1.3 < |\eta| < 2.4$  for nominal threshold  $p_T = 20$  GeV





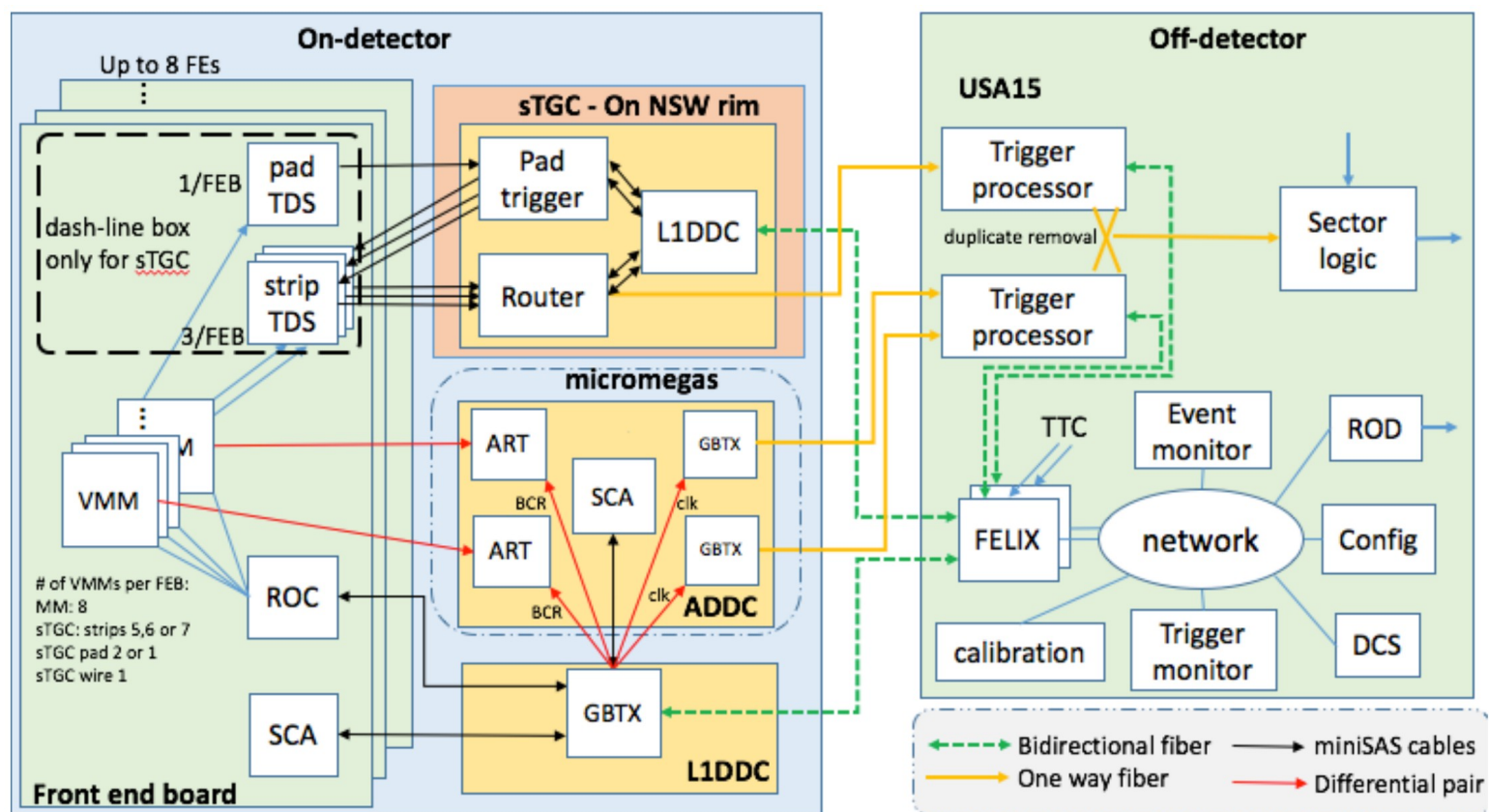
# Summary

- Upgrades of the ATLAS TGC chambers are foreseen following the LHC upgrade program
- sTGC chambers will replace part of the inner ATLAS muon station in the endcap region
  - Production is underway at all construction sites
  - Integration at CERN is progressing well
  - Performance of chambers are evaluated with cosmic muons and tests with beam at CERN
- Replacement of current EIL4 TGC doublets with triplets for the HL-LHC allows more robust triggering
- Phase-II upgrade of the TGC electronics improves TGC trigger with more refined algorithms, reducing significantly the fake trigger rate

# Backup

# sTGC Electronics

- NSW electronics overview scheme
  - Satisfy the Phase-II requirement on first-level trigger rate of 1 MHz



# Phase-II TGC PS board

- Patch Panel ASIC and Slave ASIC (PS) board has all functionalities required for the HL-LHC

## PP-ASIC

- 8 x 32 channels = 256 channels
- Eliminate timing differences, determine bunch crossing and synchronize to LHC clock

## FPGA

- Data transmitter between PP-ASIC and sector logic
- Bandwidth of 16 Gbps

## DAC and ADC

- Apply and monitor threshold voltage to ASD chips

